
HB56G51232 Series

524,288-word × 32-bit High Density Dynamic RAM Module

HITACHI

Description

The HB56G51232B/SB is a 512 k × 32 dynamic RAM module, mounted 4 pieces of 4-Mbit DRAM (HM514260CJ/CLJ) sealed in SOJ package. An outline of the HB56G51232B/SB is 72-pin single in-line package. Therefore, the HB56G51232B/SB makes high density mounting possible without surface mount technology. The HB56G51232B/SB provides common data inputs and outputs. Decoupling capacitors are mounted beside each SOJ.

Features

- 72-pin single in-line package
 - Lead pitch: 1.27 mm
- Single 5 V (± 5%) supply
- High speed
 - Access time: 70 ns/80 ns (max)
- Low power dissipation
 - Active mode: 1.6 W/1.4 W (max)
 - Standby mode: 42 mW (max)
4.2 mW (max) (L version)
- Fast page mode capability
- 512 refresh cycle: 8 ms
128 ms (L-version)
- 2 variations of refresh
 - $\overline{\text{RAS}}$ -only refresh
 - $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh
- TTL compatible

Ordering Information

Type No.	Access time	Package	Contact pad
HB56G51232B-7C/7CL	70 ns	72-pin SIP socket type	gold
HB56G51232B-8C/8CL	80 ns		
HB56G51232SB-7C/7CL	70 ns	72-pin SIP socket type	solder
HB56G51232SB-8C/8CL	80 ns		

Refer to the HB56G236B/SB-6B/7B Series.